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Thursday, 06 May 2021

09:00 - Opening

Opening

Chaired by: Heinz Wohlrabe and Alena Pietrikova

09:15 - Oral Session 1

Oral Session 1

Chaired by: Heinz Wohlrabe and Alena Pietrikova

- 09:15 KN1 **KEYNOTE: Advanced Packaging for Harsh Environment.....N/A**
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Lunch Break

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11:50 - Lunch Break

Lunch Break

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Chaired by: *Golta Kathibi and Klaus-Jürgen Wolter*

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Awarding